

The background of the cover features a complex, abstract graphic of fiber optic paths. These paths are represented by multiple parallel lines that curve and loop across the page, creating a sense of depth and movement. The lines are rendered in various shades of gray, from light to dark, against a dark gray background. The overall effect is reminiscent of a network or a series of interconnected optical fibers.

Optoelectronics/ Fiber-Optics Applications Manual

Second Edition

Prepared by The Applications Engineering Staff of the
HEWLETT-PACKARD OPTOELECTRONICS DIVISION

Stan Gage, *Applications Engineering Manager*
Dave Evans, *Applications Engineer*
Mark Hodapp, *Applications Engineer*

Hans Sorensen, *Applications Engineer*
Dick Jamison, *Applications Engineer*
Bob Krause, *Applications Engineer*

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